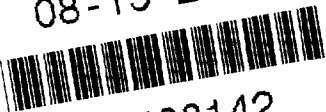


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To Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Naochika Kogure
Hiroyuki Gokuraku
Seiji Takahashi
Daisuke Imanari
Takashi Kitahama

Additional name(s) & addresses attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date July 14, 2000

2. Name and address of receiving party(ies)

Name: JSP Corporation

Internal Address: _____

Street Address: 1-1, Uchisaiwai-cho2-chome, Chiyoda-ku,City: Tokyo 100-8580 State: Japan

ZIP: _____

Additional name(s) & addresses attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

09629949

If this document is being filed together with a new application,
the execution date of the application is: July 14, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: SHERMAN & SHALLOWAY

Internal Address: _____

Street Address: 413 North Washington StreetCity: Alexandria State: VA ZIP: 223146. Total number of applications and patents involved: 17. Total fee (37 CFR 3.41).... \$ 40.00☒ Enclosed☐ Authorized to charge to deposit account8. Deposit account number: 19-1980

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and
any attached copy is a true copy of the original document.

Robert L. Haines

Name of Person Signing

Signature

August 1, 2000

Date

Total number of pages including cover sheet, attachments, and document: 2

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents & Trademarks,

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Washington, D.C. 20231

PATENT
REEL: 010989 FRAME: 0012

WHEREAS, We, Naochika Kogure, Hiroyuki Gokuraku, Seiji Takahashi, Daisuke Imanari, and Takashi Kitahama, residing respectively at 201 Mezondokyubu 'D', 808-1, Kamiyokota-cho, Utsunomiya-shi, Tochigi-ken 321-0106, Japan; 1127-70, Moritomo, Imaichi-shi, Tochigi-ken 321-2335, Japan; A-102 Terrace House, 1704-25 Tsuruta-cho, Utsunomiya-shi, Tochigi-ken 320-0851, Japan; 201 Wakabahaitsu, 1669 Komanyu-cho, Utsunomiya-shi, Tochigi-ken 320-0065, Japan; and 1126-5, Togami-cho, Utsunomiya-shi, Tochigi-ken 320-0856, Japan (hereinafter referred to as Inventors), have invented certain new and useful improvements in MULTI-LAYER EXPANSION-MOLDED ARTICLE OF POLYPROPYLENE RESIN, PRODUCTION PROCESS THEREOF, AND CONTAINER, SHOCK-ABSORBING MATERIAL FOR AUTOMOBILE AND AUTOMOTIVE MEMBER FORMED OF THE MULTI-LAYER EXPANSION-MOLDED ARTICLE OF POLYPROPYLENE RESIN; for which an application for United States Letters Patent was filed in the United States on N/A and assigned Serial Number N/A.

WHEREAS, JSP CORPORATION, a corporation of Japan, having a place of business at 1-1, Uchisaiwai-cho 2-chome, Chiyoda-ku, Tokyo 100-8580, Japan (hereinafter referred to as Company), is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to us in hand paid, the receipt whereof is hereby acknowledged, and other valuable considerations, the said Inventors have sold, assigned and transferred, and by the presents do sell, assign and transfer unto said Company, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent, which may be granted thereof in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof.

We hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Company as the assignee of the entire right, title and interest in and to the same, for the sole use and behalf of the said Company, its successors and assigns.

FURTHER, We agree that we will communicate to said Company or its representatives any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Company, make all rightful oaths and generally do everything possible to aid said Company, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, We have hereunto set our hands this 14 day of JULY, 2000.

Signed in the presence of:

Witness: Atsuo Shimizu
Atsuo Shimizu

Signed: Naochika Kogure
Naochika Kogure

Witness: Atsuo Shimizu
Atsuo Shimizu

Signed: Hiroyuki Gokuraku
Hiroyuki Gokuraku

Witness: Atsuo Shimizu
Atsuo Shimizu

Signed: Seiji Takahashi
Seiji Takahashi

Witness: Atsuo Shimizu
Atsuo Shimizu

Signed: Daisuke Imanari
Daisuke Imanari

Witness: Atsuo Shimizu
Atsuo Shimizu

Signed: Takashi Kitahama
Takashi Kitahama